

**Amendments to the Claims:**

Please amend claims 38 and 40 as follows. Following is a complete listing of the claims pending in the application, as amended:

1-37. (Cancelled)

38. (Currently Amended) A packaged microelectronic device, comprising:  
a microelectronic die having an integrated circuit and a plurality of bond-pads coupled to  
the integrated circuit;  
an interposer substrate having a first side coupled to the die, a second side opposite the  
first side, a plurality of ball-pads arranged on the second side to be coupled to a  
printed circuit board, interconnects electrically coupled to the bond-pads on the  
die and the ball-pads, a plurality of trace lines adjacent to the ball-pads, and a  
solder-mask on the second side having openings over the ball-pads, wherein at  
least a portion of at least one of the plurality of trace lines is exposed in the  
openings;  
a plurality of solder-balls arranged so that each solder-ball is in an opening in the solder-  
mask and contacting a corresponding ball-pad; and  
a dielectric compound in the openings in the solder-mask, wherein the dielectric  
compound surrounds a portion of the perimeter of each of the ball-pads and the  
solder-balls; and  
a solder paste in the openings in the solder-mask and adjacent to the dielectric compound,  
wherein such that the dielectric compound electrically insulates the solder paste,  
~~all the ball-pads and solder-balls are electrically insulated from any exposed~~  
portion of the plurality of trace lines.

39. (Original) The device of claim 38 wherein the dielectric compound includes a  
dielectric flux.

40. (Currently Amended) A packaged microelectronic device, comprising:  
a microelectronic die having an integrated circuit and at least one bond-pad coupled to the  
integrated circuit;  
an interposer substrate having a first side coupled to the die, a second side opposite the  
first side, a ball-pad on the second side, an interconnect electrically coupled to the  
bond-pad on the die and the ball-pad, a trace line adjacent to the ball-pad, and a  
solder-mask on the second side having an opening over the ball-pad and at least a  
portion of the adjacent trace line;  
a solder-ball on the ball-pad; and  
a dielectric compound in the opening in the solder-mask; and  
a solder paste in the openings in the solder-mask and adjacent to the dielectric compound,  
wherein that the dielectric compound electrically insulates the solder paste, ball-  
pad and the solder-ball from any exposed portion of the adjacent trace line in the  
opening.

41. (Original) The device of claim 40 wherein the dielectric compound includes a  
dielectric flux.

42. (Original) The device of claim 40, further comprising a circuit board having a  
contact coupled to the solder-ball.

43. (Original) The device of claim 42, further comprising a eutectic paste proximate  
to the contact.

44. (Original) The device of claim 40, further comprising a eutectic paste proximate  
to the solder-ball.

45. (Original) The device of claim 40 wherein the dielectric compound in the opening  
covers an exposed portion of the adjacent trace line.